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FQP90N10V2/FQPF90N10V2

100V N-Channel MOSFET

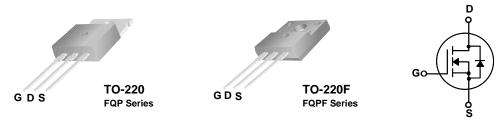
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for DC to DC converters, sychronous rectification, and other applications lowest Rds(on) is required.

Features

- 90 A, 100V, $R_{DS(on)}$ = 0.01 Ω @V_{GS} = 10 V Low gate charge (typical 147 nC)
- Low Crss (typical 300 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP90N10V2	FQPF90N10V2	Units
V _{DSS}	Drain-Source Voltage		100		V
I _D	Drain Current - Continuous (T _C = 25°C)		90	90 *	Α
	- Continuous (T _C = 100°C)		68	68 *	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	360	360 *	Α
V _{GSS}	Gate-Source Voltage		±	30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	24	130	mJ
I _{AR}	Avalanche Current	(Note 1)	9	90	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	2	25	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
P _D	Power Dissipation (T _C = 25°C)		250	83	W
	- Derate above 25°C		1.67	0.55	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175		°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300		°C

^{*} Drain current limited by maximum junction temperature.

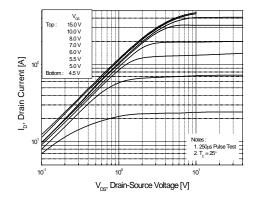
Thermal Characteristics

Symbol	Parameter	FQP90N10V2	FQPF90N10V2	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.6	1.8	°C/W
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25	i°C	0.1		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 80 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics		·			
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 45 A		8.5	10	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 45 A (No	te 4)	72		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		4730 1180	6150 1530	pF pF
C _{rss}	Reverse Transfer Capacitance	1 - 1.0 1.1.12		300	390	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time			52	114	ns
t _r	Turn-On Rise Time	$V_{DD} = 50 \text{ V}, I_{D} = 90 \text{ A},$		492	994	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$		304	618	ns
t _f	Turn-Off Fall Time	(Note	4, 5)	355	720	ns
Q _g	Total Gate Charge	V _{DS} = 80 V, I _D = 90 A,		147	191	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 30 \text{ V}, I_D = 30 \text{ V},$		28		nC
Q _{gd}	Gate-Drain Charge	(Note	4, 5)	60		nC
	Course Diede Cheresteristies ex	ad Marrimum Datings				
l _S	Source Diode Characteristics ar Maximum Continuous Drain-Source Dio				90	Α
I _{SM}		ulsed Drain-Source Diode Forward Current			360	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 90 A			1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 90 \text{ A},$		114		ns
		$dI_F/dt = 100 \text{ A/µs}$ (No				

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 0.3mH, I_{AS} = 90A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C 3. I_{SD} ≤ 90A, di/dt ≤ 200A/ μ s, V_{DD} ≤ BV_{DSS}, Starting T_{J} = 25°C 4. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

Typical Characteristics



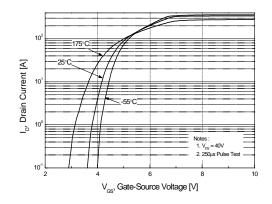
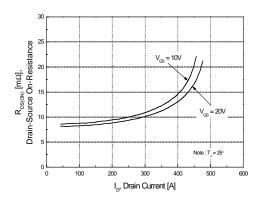


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



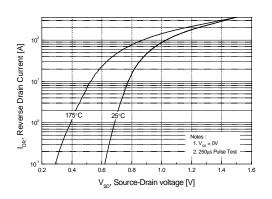
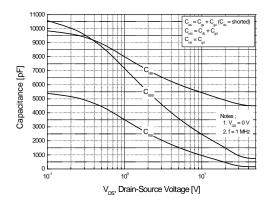


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature



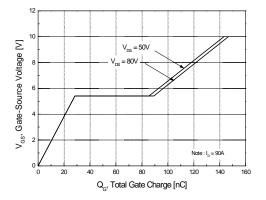


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

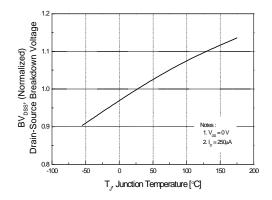


Figure 7. Breakdown Voltage Variation vs Temperature

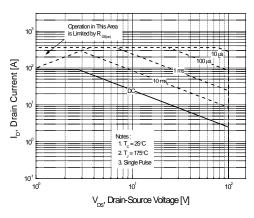


Figure 9-1. Maximum Safe Operating Area for FQP90N10V2

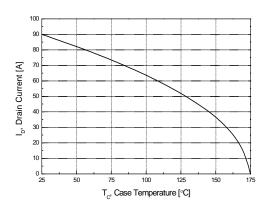


Figure 10. Maximum Drain Current vs Case Temperature

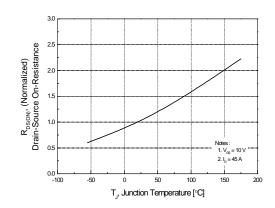


Figure 8. On-Resistance Variation vs Temperature

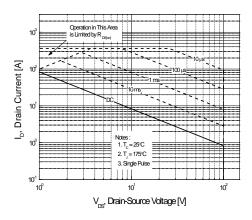


Figure 9-2. Maximum Safe Operating Area for FQPF90N10V2

Typical Characteristics (Continued)

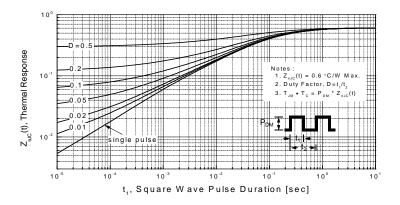


Figure 11-1. Transient Thermal Response Curve for FQP90N10V2

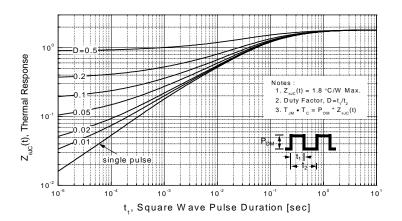
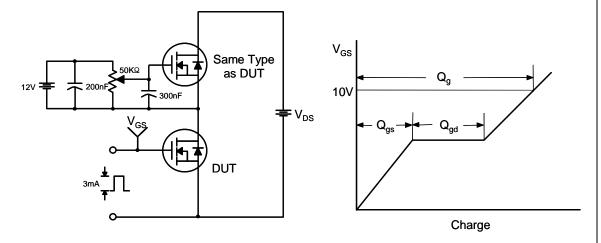
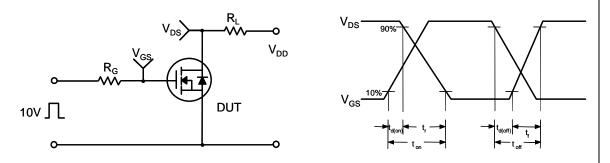


Figure 11-2. Transient Thermal Response Curve for FQPF90N10V2

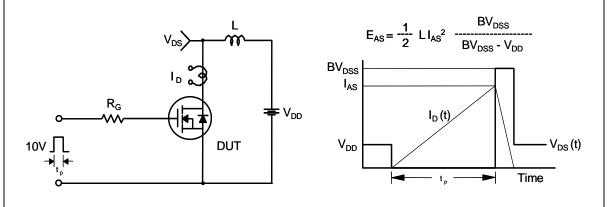
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

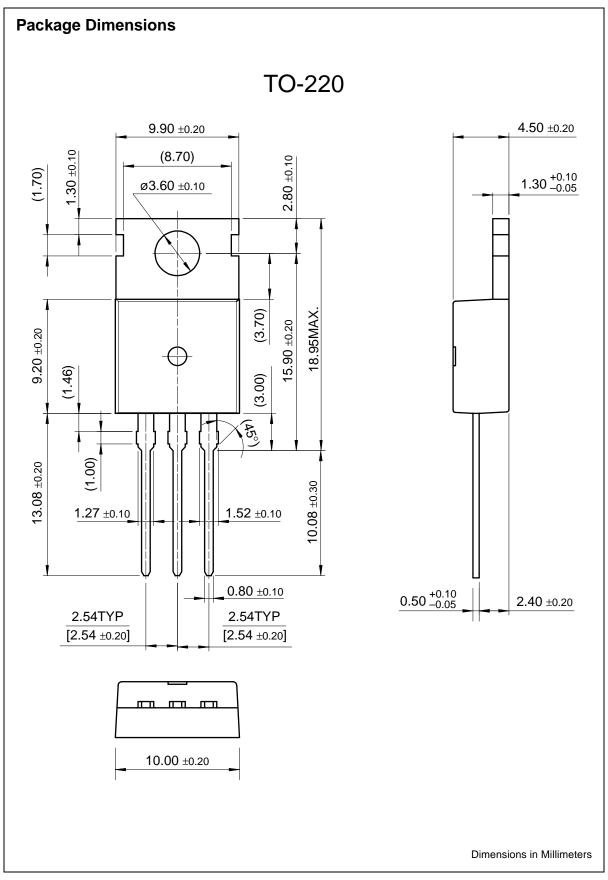


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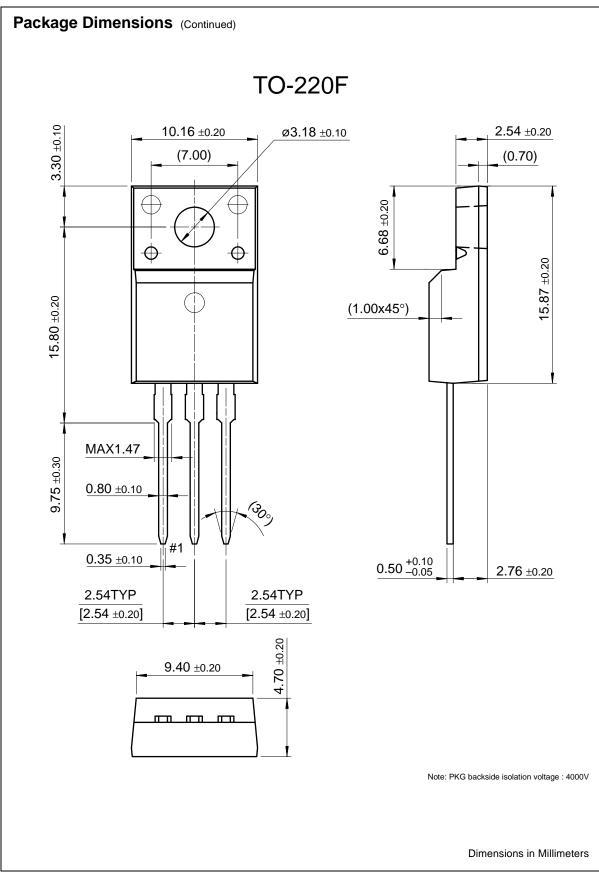
Rev. A1, April 2004

Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT Driver Same Type as DUT V_{DD} • dv/dt controlled by R_G • I_{SD} controlled by pulse period Gate Pulse Width $\mathbf{V}_{\mathbf{GS}}$ Gate Pulse Period 10V (Driver) I_{FM} , Body Diode Forward Current \mathbf{I}_{SD} di/dt (DUT) I_{RM} **Body Diode Reverse Current** V_{DS} (DUT) Body Diode Recovery dv/dt **Body Diode** Forward Voltage Drop

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